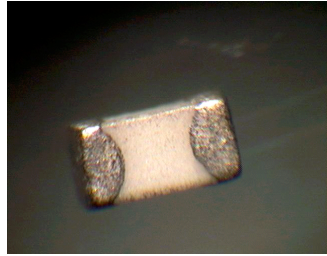


MATERIAL DATA SHEET



Material	CI160808 Series	
Product Line	Multilayer Chip Bead	
Date	04-December-2004	

NO.	Construction element	Material group	Material Weight (g)	Materials	CAS If applicable	Average mass (%)	Sum (%)	Traces
1	Ceramic Body	Ceramic	0.0024	SiO ₂	-----	Business Confidential	100	
				Al ₂ O ₃	-----			
2	Terminal	Terminal Electrode	0.00003	Ag	7440-22-4	1	100	
3	Solder Barrier	Nickel	0.00003	Ni	7440-02-0	1		
4	Solder	Tin	0.00003	Sn	7440-31-5	1	100	
5	Circuit	Silver	0.00051	Ag	7440-22-4	17	100	
		Total weight	0.003					